

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Attorney Docket No.: VISH-4123.DIV.....

Inventor(s): Frank Kuo

Group Art Unit:

Filed: 02/27/04

Examiner:

Application No.: Not yet assigned

Title: ENCAPSULATION METHOD AND LEADFRAME FOR LEADLESS SEMICONDUCTOR PACKAGES

Commissioner of Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Information Disclosure Statement Submitted Pursuant to 37 C.F.R. 1.97(b)

The citations referenced herein, copies attached, may be material to the examination of the above-identified application and are, therefore, submitted in compliance with the duty of disclosure as defined in 37 C.F.R. 1.56. The Examiner is requested to make these citations of official record in the application.

This Information Disclosure Statement submitted in accordance with 37 C.F.R. 1.97(b) is not to be construed as a representation that a search has been made, that additional items material to the examination of this application do not exist, or that any one or more of these citations constitute prior art under 35 U.S.C. 102.

The Examiner's attention is respectfully directed to the following U.S. Patents:

<u>Pat. No.</u>	<u>Pat. Title</u>	<u>Grant Date</u>
5,645,864	RESIN ENCAPSULATING MOLDING DIE FOR MANUFACTURING A SEMICONDUCTOR DEVICE	07/08/97
6,319,450	ENCAPSULATED CIRCUIT USING VENTED MOLD	11/20/01
5,052,907	RESIN SEALING APPARATUS FOR USE IN MANUFACTURING A RESIN-SEALED SEMICONDUCTOR DEVICE	10/01/91
6,214,273	MOLDING METHOD WITH THE USE OF MODIFIED RUNNERS	04/10/01
5,672,550	METHOD OF ENCAPSULATING SEMICONDUCTOR DEVICES USING A LEAD FRAME WITH RESIN TABLETS ARRANGED ON LEAD FRAME	09/30/97
4,900,501	METHOD AND APPPARATUS FOR ENCAPSULATING SEMI-CONDUCTORS	02/13/90

The Examiner's attention is respectfully directed to the following Foreign Patent or Published Foreign Patents:

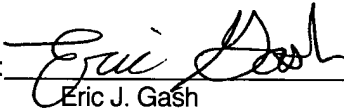
<u>Document No.</u>	<u>Title</u>	<u>Publication Date</u>
JP2000031180A	PRODUCTION OF SEMICONDUCTOR DEVICE	01/28/00
JP358128745A	PLASTIC-FORMING MOLD FOR SEALED SEMI-CONDUCTOR IN RESIN	08/01/83

Please direct all correspondence concerning the above-identified application to the following address:

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Respectfully submitted,

Date: February 27, 2004

By:   
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Patent Application

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**Form 1449**

**U.S. Patent Documents**

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	5,645,864	07/08/97	Higuchi	425	116	04/25/96
	B	6,319,450	11/20/01	Chua et al.	264	272.17	07/12/99
	C	5,052,907	10/01/91	Matumoto et al.	425	116	07/03/90
	D	6,214,273	04/10/01	Liang et al.	264	272.14	11/10/98
	E	5,672,550	09/30/97	Tsuji et al.	437	219	01/10/96
	F	4,900,501	02/13/90	Saeki et al.	264	272.17	10/30/86

**Foreign Patent or Published Foreign Patent Application**

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	G	JP2000031180A	01/28/00	JPO	H01L021	56		x
	H	JP358128745A	08/01/83	JPO	H01L021	56		x

**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	I	
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.